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January 2015

FPF2280 Over-Voltage Protection Load Switch

Features

- Surge Protection
 - IEC 61000-4-5: > 100 V
- Over-Voltage Protection (OVP)
- Over-Temperature Protection (OTP)
- ESD Protection
 - Human Body Model (HBM): > 3.5 kV
 - Charged Device Model (CDM): > 2 kV
 - IEC 61000-4-2 Air Discharge: > 15 kV
 - IEC 61000-4-2 Contact Discharge: > 8 kV

Applications

- Mobile Handsets and Tablets
- Portable Media Players
- MP3 Players

Description

The FPF2280 features a low-R_{ON} internal FET and an operating range of 2.5 V_{DC} to 5.5 V_{DC} (absolute maximum of 29 V_{DC}). An internal clamp is capable of shunting surge voltages >100 V, protecting downstream components and enhancing system robustness. The FPF2280 features over-voltage protection that powers down the internal FET if the input voltage exceeds the OVP threshold. The OVP threshold is adjustable with optional external resistors. Over-temperature protection also powers down the device at 130°C (typical). Exceptionally low off-state current (<1 μ A maximum) facilitates compliance with standby power requirements.

The FPF2280 is available in a fully "green" compliant 1.3 mm × 1.8 mm Wafer-Level Chip-Scale Package (WLCSP) with backside laminate.

Related Resources

http://www.fairchildsemi.com/

Ordering Information

| Part Number | Operating Temperature Range | Top Mark | Package | Packing Method |
|------------------|--------------------------------|----------|-----------------------------|-------------------|
| FPF2280BUCX_F130 | -40°C – 105°C | HC | 12-Ball, 0.4 mm Pitch WLCSP | Tape & Reel |

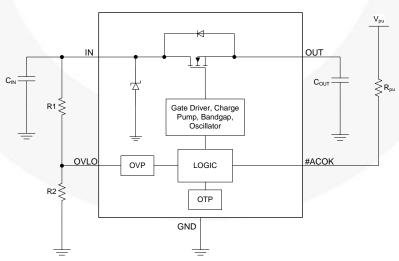
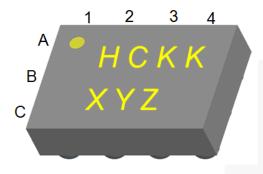


Figure 1. Functional Block Diagram

Pin Configuration



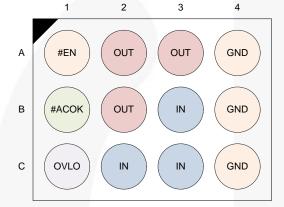
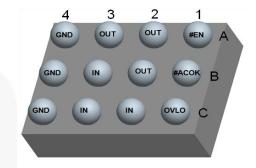


Figure 2. Pin Configuration (Top View)



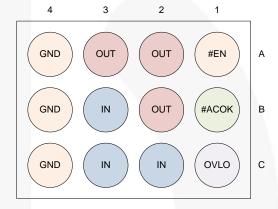


Figure 3. Pin Configuration (Bottom View)

Pin Definitions

| Name | Bump | Туре | Description | | | | |
|------------|-----------------|--------------|-------------------------------------|---|--|--|--|
| IN | B3, C2, C3 | Input/Supply | Switch Input and Device Supply | | | | |
| OUT | A2, A3, B2 | Output | Switch Output to Load | | | | |
| #ACOK | #ACOK B1 Output | | Power Good | 1 | $V_{IN} < V_{IN_min} \text{ or } V_{IN} \ge V_{OVLO}$ | | |
| #ACOK BI | | (Open Drain) | | 0 | Voltage Stable | | |
| #EN | A1 | Input | Device Enable (Active LOW) | | | | |
| OVLO | C1 | Input | Over-Voltage Lockout Adjustment Pin | | | | |
| GND | A4, B4, C4 | Supply | Device Ground | | | | |

Over-Voltage Lockout (OVLO) Calculation

OVLO can be set externally and override default OVP. By connecting an external resistor-driver to the OVLO pin. Equation (1) can produce the desired trip voltage and resistor values.

$$V_{IN_OLVO} = V_{OVLO_TH} \times [1 + R1/R2]$$
 (1)
Recommended minimum R1 = 1 M Ω .

On-The-Go (OTG) Functionality

During OTG operation, the FPF2280 is initially disabled and the power FET's bulk diode is forward biased. The bulk diode represents ~0.7 V drop across the device, which remains until the V_IN voltage increases past 2.5 V, when the device is fully enabled. While the device is disabled and the body diode is forward biased, the max DC current through the diode is 1.8 A. This current is limited by the thermal performance of the device

(0.7~Vx~1.8~A=1.36~W). This current should be transient; the #EN pin must be pulled LOW to ensure the device fully enables. The transient should not exceed the RC time constant of the C_IN and C_OUT capacitors. At the system level, over-voltage and current protection should be provided outside the FPF2280.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | | | Max. | Unit |
|-----------------------|---|---------|------|-----------------------|------|
| V _{IN} | V_IN to GND & V_IN to V_OUT = GND or Float | | -0.3 | 29.0 | V |
| V _{OUT} | V_OUT to GND | 1 | -0.3 | V _{IN} + 0.3 | V |
| V _{OVLO} | OVLO to GND | | -0.3 | 24.0 | ٧ |
| V _{#EN_ACOK} | Maximum DC Voltage Allowed on #EN or ACOK Pin | | | 6 | V |
| I _{IN} | Switch I/O Current (Continuous) | 1 | | 4.5 | Α |
| t _{PD} | Total Power Dissipation at T _A = 25°C | | | 1.48 | W |
| T _{STG} | Storage Temperature Range | | -65 | +150 | °C |
| TJ | Maximum Junction Temperature | | | +150 | °C |
| TL | Lead Temperature (Soldering, 10 Seconds) | | | +260 | °C |
| Θ_{JA} | Thermal Resistance, Junction-to-Ambient ⁽¹⁾ (1-in. ² Pad of 2-oz. Copper) | | | 84.1 | °C/W |
| | IEC 61000-4-2 System ESD | Air Gap | 15.0 | | |
| FCD | | Contact | 8.0 | | 137 |
| ESD | Human Body Model, ANSI/ESDA/JEDEC JS-001-2012 All | | 3.5 | | kV |
| | Charged Device Model, JESD22-C101 All Pins | | | | |
| Surge | IEC 61000-4-5, Surge Protection V _{IN} | | | | V |

Note:

Measured using 2S2P JEDEC std. PCB.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

| Symbol | Parameter | Min. | Max. | Unit |
|-----------------|-----------------------|------|------|------|
| V_{IN} | Supply Voltage | 2.5 | 20.0 | V |
| T_A | Operating Temperature | -40 | +105 | °C |

Electrical Characteristics

 $T_A = -40^{\circ}C$ to $105^{\circ}C$ unless otherwise indicated. Typical values are $V_{IN} = 5.0$ V, $I_{IN} \le 3$ A, $C_{IN} = 0.1$ μF and $T_A = 25^{\circ}C$.

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|--------------------------|---|---|------|------|------|------|
| V _{IN_CLAMP} | Input Clamping Voltage | I _{IN} = 10 mA | | 35 | | V |
| IQ | Input Quiescent Current | V _{IN} = 5 V, #EN = 0 V | | 58 | 100 | μΑ |
| I _{IN_Q} | OVLO Supply Current | $V_{OVLO} = 3 \text{ V}, V_{IN} = 5 \text{ V}, V_{OUT} = 0 \text{ V}$ | | 63 | 100 | μA |
| V | Internal Over Veltere Trip I evel | V _{IN} Rising, OVLO = GND | 6.6 | 6.8 | 7.0 | V |
| V_{IN_OVLO} | Internal Over-Voltage Trip Level | V _{IN} Falling | 6.2 | | | V |
| $V_{\text{OVLO_TH}}$ | OVLO Set Threshold | $V_{IN} = 2.5 \text{ V to } V_{OVLO}$ | 1.12 | 1.20 | 1.24 | V |
| V_{OVLO_RNG} | Adjustable OVLO Threshold Range | V _{IN} = 2.5 V to V _{OVLO} | 4 | | 20 | V |
| V _{OVLO_SELECT} | External OVLO Select Threshold | | | 0.30 | 0.28 | V |
| R _{ON} | Resistance from V _{IN} to V _{OUT} | V _{IN} = 5 V, I _{OUT} = 1 A. T _A = 25°C | | 30 | 39 | mΩ |
| C _{OUT} | OUT Load Capacitance ⁽²⁾ | V _{IN} = 5 V | | | 1000 | μF |
| I _{OLVO} | OVLO Input Leakage Current | V _{OVLO} = V _{OVLO_TH} | -100 | | 100 | nA |
| T _{SDN} | Thermal Shutdown ⁽²⁾ | | | 130 | A | °C |
| T _{SDN_HYS} | Thermal Shutdown Hysteresis ⁽²⁾ | | | 20 | | °C |
| Digital Signa | als | | | | | |
| V _{OL} | #ACOK Output Low Voltage | $V_{I/O} = 3.3 \text{ V}, I_{SINK} = 1 \text{ mA}$ | | | 0.4 | V |
| VIH_#EN | Enable HIGH Voltage | $V_{IN} = 2.5 \text{ V to } V_{OVLO}$ | 1.2 | | | V |
| VIL_#EN | Enable LOW Voltage | $V_{IN} = 2.5 \text{ V to } V_{OVLO}$ | | | 0.5 | V |
| I _{ACOK_LEAK} | #ACOK Leakage Current | V _{I/O} = 3.3 V, #ACOK Deasserted, #EN = 0 V | -0.5 | | 0.5 | μA |
| #EN_Leak | #EN Leakage Current | V _{IN} = 5.0 V, V _{OUT} = Float | -1.0 | | 1.0 | μΑ |
| Timing Char | acteristics | | - 7 | | | |
| t _{DEB} | Debounce Time | Time from 2.5 V < V_{IN} < V_{IN_OVLO} to V_{OUT} = 0.1 \times V_{IN} | | 15 | / | ms |
| t _{START} | Soft-Start Time | Time from $V_{IN} = V_{IN_min}$ to $0.2 \times \text{\#ACOK}$, $V_{IO} = 1.8 \text{ V}$ with $10 \text{ k}\Omega$ Pull-up Resistor | | 30 | | ms |
| t _{ON} | Switch Turn-On Time | $\begin{array}{l} V_{IN}=5~V,~R_L=100~\Omega,~V_{OUT}~from\\ 0.1~\times~V_{IN}~to~0.9~\times~V_{IN},~C_{LOAD}=\\ 100~\mu F \end{array}$ | | 2 | | ms |
| toff | Switch Turn-Off Time ⁽²⁾ | R_L = 100 Ω , C_L = 0 μ F, V_{IN} > V_{OVLO} to V_{OUT} = 0.8 \times V_{IN} | | 125 | | ns |

Note:

2. Guaranteed by characterization and design.

Timing Diagrams

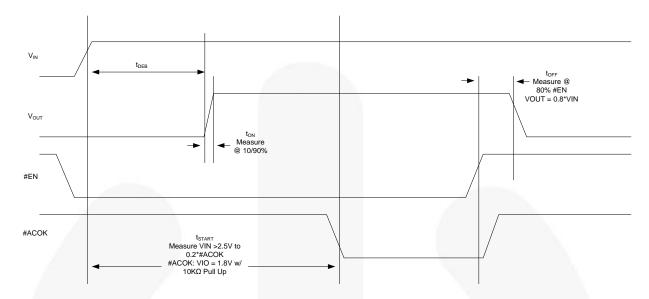


Figure 4. Timing for Power Up and Normal Operation

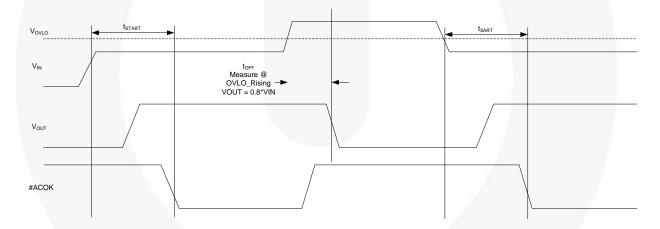
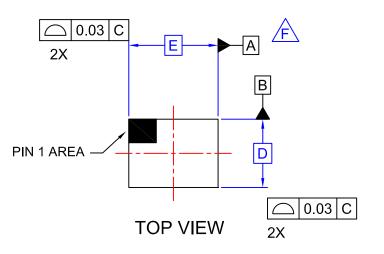
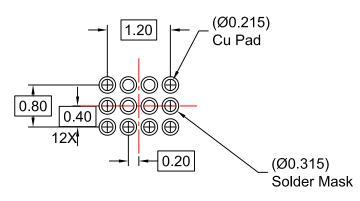


Figure 5. Timing for OVLO Trip

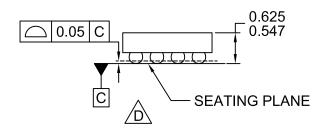
Product-Specific Package Dimensions

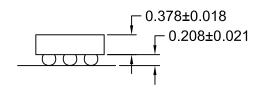
| D | E | X | Y |
|----------------|----------------|---------------|---------------|
| 1288 μm ±30 μm | 1828 μm ±30 μm | 314 μm ±18 μm | 244 μm ±18 μm |





RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





SIDE VIEWS

(X)±0.018 ⊕ 0.005(M) C A B ⊕ 0.005(M) C A B Ø0.260±0.02 12X (Y)±0.018

BOTTOM VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- G. DRAWING FILENAME: MKT-UC012ZCrev2.
- H. FAIRCHILD SEMICONDUCTOR RECOMMENDS THAT LANDS IN THE LANDPATTERN ARE AT LEAST .215MM DIAMETER AS MEASURED AT THE BOTTOM OF THE LAND, NOT THE TOP EDGE.

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